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Revision History

<table>
<thead>
<tr>
<th>Revision</th>
<th>Notes</th>
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<tbody>
<tr>
<td>E2</td>
<td>Add C60, Change R2 to C61, Add new R2 to U12 nEN circuit, Make R28 DNI. Add Nets U11_IOVDD, +5V_ENn</td>
</tr>
<tr>
<td>E3</td>
<td>Remove USB, rearrange schematic around the Detector Socket</td>
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PCB Number: IS4014
PCB Rev: E3

Label Table

<table>
<thead>
<tr>
<th>Variant</th>
<th>Label Text</th>
</tr>
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<tbody>
<tr>
<td>001</td>
<td>S/N xxxx</td>
</tr>
</tbody>
</table>

Assembly Note

ZZ1 Install label in silkscreened box after final wash. Text shall be 8 pt. font. Text shall be per the Label Table in PDF schematic.

ZZ2 Variant name not interpreted

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ZZ4 Components BL1 and U5 must be assembled to U5 before U5 is attached to the board.

ZZ5 Remove protective coverings from BL1 and U5.

ZZ6 Slide pins of U5 into holes of BL1. BL1 must lie flat on the back of U5.

ZZ7 U8 is to be inserted into the holes for J4 and J6 through J20 with U8 pin 1 in J4.
Analog Front End
Current Source for Detector Temperature Monitor

Logic Level Translator

Detecter Socket

PIR Sensor

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